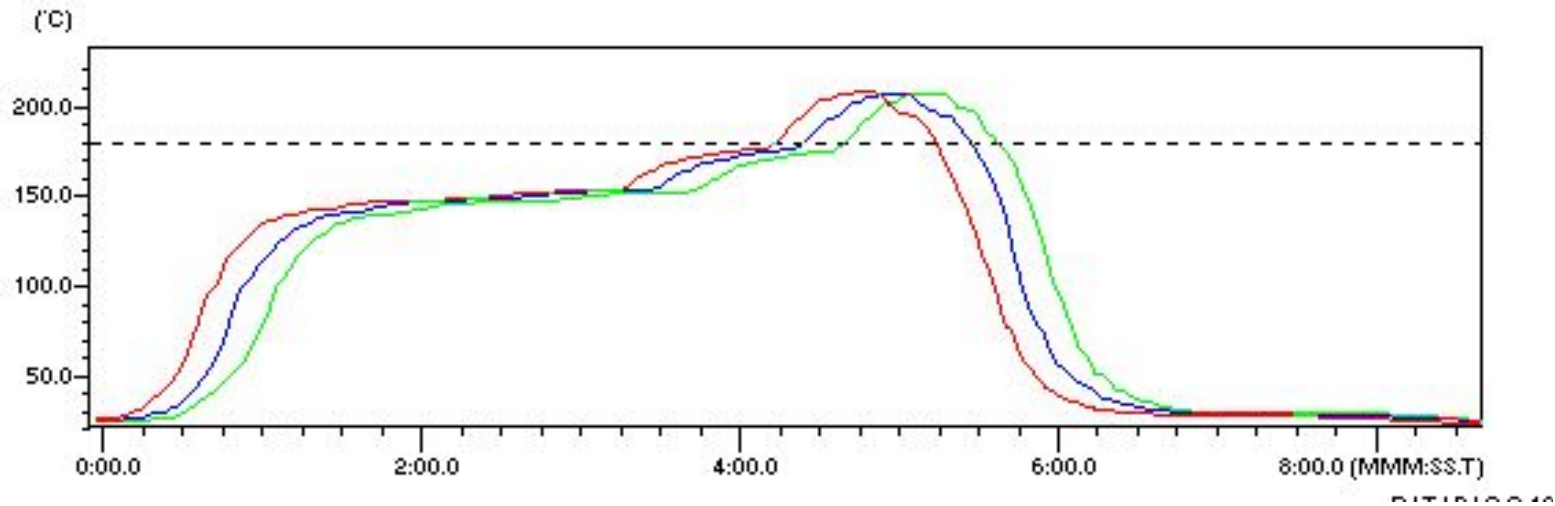




Recommended Reflow Profile for 63Sn/37Pb or 62Sn/36Pb/2Ag Solder Paste



This profile is designed for use with Sn63 or Sn62 and can serve as a general guideline in establishing a reflow profile.

Reflow Profile:

- Heating-up @1~3°C/sec to 140°C
- Preheat @ 140-150°C for 120 ~ 160 sec
- Ramp @ 2~3 °C/sec to peak temperature (220 ~ 225 °C),
Temperature over 183°C for 45~ 75 sec
- Cooling down to room temperature @4~2°C/sec to avoid undesired intermetallic compound layer.